

# 2 OUTPUT PCIE GEN1/2 SYNTHESIZER

#### IDT5V41065

# **Recommended Applications**

2 Output synthesizer for PCIe Gen1/2 and Ethernet

# **General Description**

The IDT5V41065 is a PCIe Gen2 compliant spread spectrum capable clock generator. The device has 2 differential HCSL outputs and can be used in communication or embedded systems to substantially reduce electro-magnetic interference (EMI). The spread amount and output frequency are selectable via select pins. The IDT5V41065 can also supply 25 MHz, 125 MHz and 200 MHz outputs for applications such as Ethernet.

# **Output Features**

2 - 0.7V current mode differential HCSL output pairs

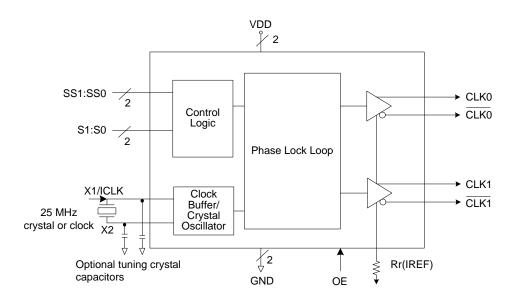
#### Features/Benefits

- 16-pin TSSOP and QFN packages; small board footprint
- Spread-spectrum capable; reduces EMI
- Outputs can be terminated to LVDS; can drive a wider variety of devices
- 25 MHz, 125 MHz and 200 MHz output frequencies; TSSOP only
- 100MHz and 200MHz output frequencies; VFQFPN package
- OE control pin; greater system power management
- Spread% and frequency pin selection; no software required to configure device
- Industrial temperature range available; supports demanding embedded applications
- For PCle Gen3 applications, see the 5V41235

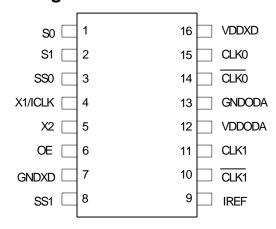
# **Key Specifications**

- Cycle-to-cycle jitter < 100 ps
- Output-to-output skew < 50 ps</li>
- PCIe Gen2 phase jitter < 3.0ps RMS

# **Block Diagram**



# **Pin Assignment**



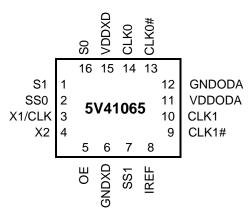
16-pin (173 mil) TSSOP

# Output Select Table 1 (MHz)-TSSOP only

S1	S0	CLK(1:0), CLK(1:0)
0	0	25M
0	1	100M
1	0	125M
1	1	200M

# **Spread Selection Table 2-TSSOP only**

SS1	SS0	Spread%
0	0	No Spread
0	1	Down -0.5
1	0	Down -0.75
1	1	No Spread



16-pin VFQFPN

# **Output/Spread Select Table 3 - VFQFPN Only**

S1	S0	SS1	SS0	Output	Spread%	
0	0	0	0	100MHz	-0.5	
0	0	0	1	200MHz	-0.5	
0	0	1	0	100MHz	No spread	
0	0	1	1	Res	served	
0	1	0	0	100MHz	-1	
0	1	0	1	200MHz	-1	
0	1	1	0	Res	served	
0	1	1	1	Reserved		
1	0	0	0	100MHz	-1.5	
1	0	0	1	200MHz	-1.5	
1	0	1	0	Res	served	
1	0	1	1	Res	served	
1	1	0	0	Reserved		
1	1	0	1	200MHz No spread		
1	1	1	0	Reserved		
1	1	1	1	Res	served	

# **Pin Descriptions**

VFQFPN	TSSOP	Pin	Pin	Pin Description
Pin	Pin	Name	Type	
Number	Number			
16	1	S0	Input	Select pin 0. See Table1. Internal pull-up resistor.
1	2	S1	Input	Select pin 1. See Table 1. Internal pull-up resistor.
2	3	SS0	Input	Spread Select pin 0. See Table 2. Internal pull-up resistor.
3	4	X1/ICLK	Input	Crystal or clock input. Connect to a 25 MHz crystal or single ended clock.
4	5	X2	Output	Crystal connection. Leave unconnected for clock input.
5	6	OE	Input	Output enable. Tri-states outputs and device is not shut down. Internal pull-up resistor.
6	7	GNDXD	Power	Connect to ground.
7	8	SS1	Input	Spread Select pin 1. See Table 2. Internal pull-up resistor.
8	9	IREF	Output	Precision resistor attached to this pin is connected to the internal current reference.
9	10	CLK1	Output	HCSL complementary clock output 1.
10	11	CLK1	Output	HCSL true clock output 1.
11	12	VDDODA	Power	Connect to voltage supply +3.3 V for output driver and analog circuits
12	13	GNDODA	Power	Connect to ground.
13	14	CLK0	Output	HCSL complementary clock output 0.
14	15	CLK0	Output	HCSL true clock output 0.
15	16	VDDXD	Power	Connect to voltage supply +3.3 V for crystal oscillator and digital circuit.

# **Applications Information**

#### **External Components**

A minimum number of external components are required for proper operation.

# **Decoupling Capacitors**

Decoupling capacitors of 0.01  $\mu F$  should be connected between each VDD pin and the ground plane, as close to the VDD pin as possible. Do not share ground vias between components. Route power from power source through the capacitor pad and then into ICS pin.

#### Crystal

A 25 MHz fundamental mode parallel resonant crystal should be used. This crystal must have less than 300 ppm of error across temperature in order for the IDT5V41065 to meet PCI Express specifications.

#### **Crystal Capacitors**

Crystal capacitors are connected from pins X1 to ground and X2 to ground to optimize the accuracy of the output frequency.

C<sub>L</sub>= Crystal's load capacitance in pF

Crystal Capacitors (pF) =  $(C_1 - 8) * 2$ 

For example, for a crystal with a 16 pF load cap, each external crystal cap would be 16 pF. (16-8)\*2=16.

Current Source (Iref) Reference Resistor - RR

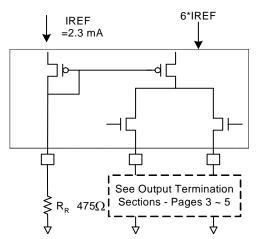
If board target trace impedance (Z) is  $50\Omega$ , then  $R_R$  =  $475\Omega$  (1%), providing IREF of 2.32 mA. The output current (I<sub>OH</sub>) is equal to 6\*IREF.

**Output Termination** 

The PCI-Express differential clock outputs of the IDT5V41065 are open source drivers and require an external series resistor and a resistor to ground. These resistor values and their allowable locations are shown in detail in the **PCI-Express Layout Guidelines** section.

The IDT5V41065 can also be configured for LVDS compatible voltage levels. See the LVDS Compatible Layout Guidelines section.

# **Output Structures**



# **General PCB Layout Recommendations**

For optimum device performance and lowest output phase noise, the following guidelines should be observed.

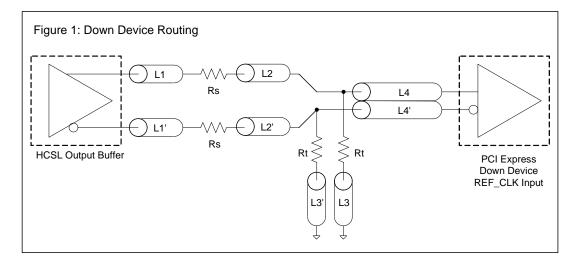
- 1. Each  $0.01\mu F$  decoupling capacitor should be mounted on the component side of the board as close to the VDD pin as possible.
- 2. No vias should be used between decoupling capacitor and VDD pin.
- 3. The PCB trace to VDD pin should be kept as short as possible, as should the PCB trace to the ground via. Distance of the ferrite bead and bulk decoupling from the device is less critical.
- 4. An optimum layout is one with all components on the same side of the board, minimizing vias through other signal layers (any ferrite beads and bulk decoupling capacitors can be mounted on the back). Other signal traces should be routed away from the IDT5V41065. This includes signal traces just underneath the device, or on layers adjacent to the ground plane layer used by the device.

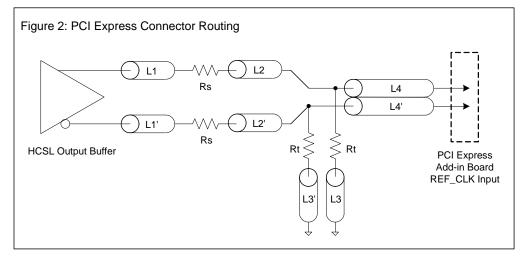
# **Layout Guidelines**

SRC Reference Clock							
Common Recommendations for Differential Routing	Dimension or Value	Unit	Figure				
L1 length, route as non-coupled 50ohm trace	0.5 max	inch	1				
L2 length, route as non-coupled 50ohm trace	0.2 max	inch	1				
L3 length, route as non-coupled 50ohm trace	0.2 max	inch	1				
Rs	33	ohm	1				
Rt	49.9	ohm	1				

Down Device Differential Routing			
L4 length, route as coupled microstrip 100ohm differential trace	2 min to 16 max	inch	1
L4 length, route as coupled stripline 100ohm differential trace	1.8 min to 14.4 max	inch	1

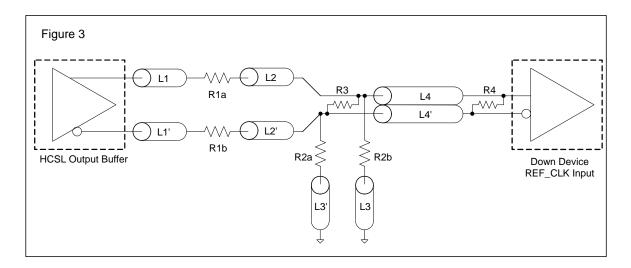
Differential Routing to PCI Express Connector			
L4 length, route as coupled microstrip 100ohm differential trace	0.25 to 14 max	inch	2
L4 length, route as coupled stripline 100ohm differential trace	0.225 min to 12.6 max	inch	2



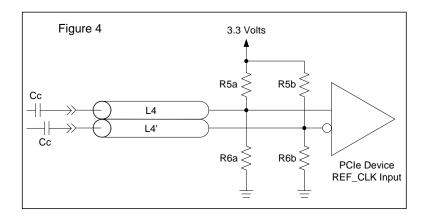


	Alternative Termination for LVDS and other Common Differential Signals (figure 3)								
Vdiff Vp-p Vcm R1 R2 R3 R4 Note							Note		
0.45 v	0.22v	1.08	33	150	100	100			
0.58	0.28	0.6	33	78.7	137	100			
0.80	0.40	0.6	33	78.7	none	100	ICS874003i-02 input compatible		
0.60	0.3	1.2	33	174	140	100	Standard LVDS		

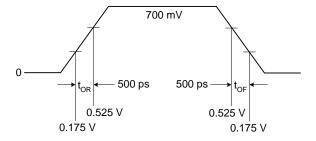
R1a = R1b = R1R2a = R2b = R2



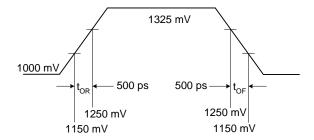
Cable Connected AC Coupled Application (figure 4)					
Component	Value	Note			
R5a, R5b	8.2K 5%				
R6a, R6b	1K 5%				
Cc	0.1 μF				
Vcm	0.350 volts				



# Typical PCI-Express (HCSL) Waveform



# **Typical LVDS Waveform**



# **Absolute Maximum Ratings**

Stresses above the ratings listed below can cause permanent damage to the IDT5V41065. These ratings are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDDXD, VDDODA	4.6 V
All Inputs and Outputs	-0.5 V to VDD+0.5 V
Ambient Operating Temperature (commercial)	0 to +70°C
Ambient Operating Temperature (industrial)	-40 to +85°C
Storage Temperature	-65 to +150°C
Junction Temperature	125°C
Soldering Temperature	260°C
ESD Protection (Input)	2000 V min. (HBM)

# **DC Electrical Characteristics**

Unless stated otherwise, VDD = 3.3 V ±5%, Ambient Temperature -40 to +85°C

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Supply Voltage	V		3.135	3.3	3.465	V
Input High Voltage <sup>1</sup>	V <sub>IH</sub>	S0, S1, OE, ICLK, SS0, SS1	2.2		VDD +0.3	V
Input Low Voltage <sup>1</sup>	$V_{IL}$	S0, S1, OE, ICLK, SS0, SS1	VSS-0.3		0.8	V
Input Leakage Current <sup>2</sup>	I <sub>IL</sub>	0 < Vin < VDD	-5		5	μΑ
Operating Supply Current	I <sub>DD</sub>	$R_S$ =33 $\Omega$ , $R_P$ =50 $\Omega$ , $C_L$ =2 pF		63	85	mA
@100 MHz	I <sub>DDOE</sub>	OE =Low		42	50	mA
Input Capacitance	C <sub>IN</sub>	Input pin capacitance			7	pF
Output Capacitance	C <sub>OUT</sub>	Output pin capacitance			6	pF
X1, X2 Capacitance	C <sub>INX</sub>				5	pF
Pin Inductance	L <sub>PIN</sub>				5	nΗ
Output Impedance	Z <sub>O</sub>	CLK outputs	3.0			kΩ
Pull-up Resistor	R <sub>PU</sub>	S0, S1, OE, SS0, SS1		100		kΩ

- 1. Single edge is monotonic when transitioning through region.
- 2. Inputs with pull-ups/-downs are not included.

# AC Electrical Characteristics - CLK0/CLK1, CLK0/CLK1

Unless stated otherwise, VDD=3.3 V ±5%, Ambient Temperature -40 to +85°C

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency				25		MHz
Output Frequency		HCSL termination	25		200	MHz
		LVDS termination	25		100	MHz
Output High Voltage <sup>1,2</sup>	V <sub>OH</sub>	HCSL			850	mV
Output Low Voltage <sup>1,2</sup>	V <sub>OL</sub>	HCSL	-150			mV
Crossing Point Voltage <sup>1,2</sup>		Absolute	250		550	mV
Crossing Point Voltage <sup>1,2,4</sup>		Variation over all edges			140	mV
Jitter, Cycle-to-Cycle <sup>1,3</sup>					100	ps
Frequency Synthesis Error		All outputs		0		ppm
Modulation Frequency		Spread spectrum	30	32.9	33	kHz
Rise Time <sup>1,2</sup>	t <sub>OR</sub>	From 0.175 V to 0.525 V	175		700	ps
Fall Time <sup>1,2</sup>	t <sub>OF</sub>	From 0.525 V to 0.175 V	175		700	ps
Rise/Fall Time Variation <sup>1,2</sup>					125	ps
Output to Output Skew					50	ps
Duty Cycle <sup>1,3</sup>			45		55	%
Output Enable Time <sup>5</sup>		All outputs		50	100	ns
Output Disable Time <sup>5</sup>		All outputs		50	100	ns
Stabilization Time	t <sub>STABLE</sub>	From power-up VDD=3.3 V			1.8	ms
Spread Spectrum Transition Time	t <sub>SPREAD</sub>	Stabilization time after spread spectrum changes	7		30	ms

- Note 1: Test setup is  $R_S=33\Omega$ ,  $R_P=50\Omega$  with  $C_I=2$  pF,  $R_I=475\Omega$  (1%).
- Note 2: Measurement taken from a single-ended waveform.
- Note 3: Measurement taken from a differential waveform.
- Note 4: Measured at the crossing point where instantaneous voltages of both CLK and  $\overline{\text{CLK}}$  are equal.
- Note 5: CLK pins are tri-stated when OE is low asserted. CLK is driven differential when OE is high.

# **Electrical Characteristics - Differential Phase Jitter**

Parameter	Symbol	Conditions	Min	Тур	Max	Units	Notes
	t <sub>jphasePLL</sub>	PCle Gen1		32	86	ps (p-p)	1,2,3
Jitter, Phase	t <sub>jphaseLO</sub>	PCIe Gen2, 10 kHz < f < 1.5 MHz		8.0	3	ps (RMS)	1,2,3
	t <sub>jphaseHIGH</sub>	PCIe Gen2, 1.5 MHz < f < Nyquist (50 MHz)		2.3	3.1	ps (RMS)	1,2,3

- Note 1. Guaranteed by design and characterization, not 100% tested in production.
- Note 2. See http://www.pcisig.com for complete specs.
- Note 3: Applies to 100MHz, spread off and 0.5% down spread only.

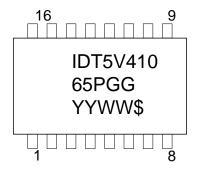
# **Thermal Characteristics (16TSSOP)**

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Thermal Resistance Junction to	$\theta_{\sf JA}$	Still air		78		°C/W
Ambient	$\theta_{\sf JA}$	1 m/s air flow		70		°C/W
	$\theta_{\sf JA}$	3 m/s air flow		68		°C/W
Thermal Resistance Junction to Case	$\theta_{\sf JC}$			37		°C/W

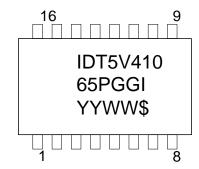
# Thermal Characteristics(16VFQFPN)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Thermal Resistance Junction to	$\theta_{\sf JA}$	Still air		63.2		°C/W
Ambient	$\theta_{\sf JA}$	1 m/s air flow		55.9		°C/W
	$\theta_{\sf JA}$	3 m/s air flow		51.4		°C/W
Thermal Resistance Junction to Case	$\theta$ JC			65.8		°C/W

# Marking Diagram (5V41065PGG)



# Marking Diagram (5V41065PGGI)



#### Notes:

- 1. Line 1 and 2: IDT part number.
- 2. Line 3: YYWW Date code; \$ Assembly location.
- 3. "G" after the two-letter package code designates RoHS compliant package.
- 4. "I" at the end of part number indicates industrial temperature range.
- 5. Bottom marking: country of origin if not USA.

# **Marking Diagram (5V41065NLGI)**



# **Marking Diagram (5V41065NLGI)**



#### Notes:

- 1. Line 1: Lot number.
- 2. Line 2: YWW Date code; \$ Assembly location.
- 3. "G" designates RoHS compliant package.
- 4. "I" at the end of part number indicates industrial temperature range.

Package Outline and Package Dimensions (16-pin QFN)

# IDT5V41065 APRIL 17, 2017

#### IDT® 2 OUTPUT PCIE GEN1/2 SYNTHESIZER REVISIONS DATE APPROVED REV DESCRIPTION RC 00 INITIAL RELEASE 10/15/08 KS 01 COMBINE POD & LAND PATTERN 9/17/13 -PIN #1 IDENTIFICATION Pin 1 Dot 1.700±0.10 Exp. DAP - 3.000±0.1 — By Marking 0.400±0.10 0.500 Bsc 1.700±0.10 Exp. DAP 3.000±0.10 0.23<u>0±0.050</u> 0.400±0.050 1.500 Ref. TOP VIEW VIEW -0.900±0.10 0.20 REF 0.000-0.050 (0.5MM PITCH) 16LD QFN 3X3 TOLERANCES UNLESS SPECIFIED DECIMAL ANGULA XX± ± XXXX± XXXX± 6024 Silver Creek Valley Road San Jose, CA 95138 PHONE: (408) 284–8200 WWW.IDT.com FAX: (408) 284–8591 ANGULAR APPROVALS DATE DRAWN RAC 10/15/08 CHECKED TITLE NL/NLG16 PACKAGE OUTLINE 3.0 x 3.0 mm BODY 0.5 mm PITCH QFN SIZE DRAWING No. REV 01 C PSC-4169 DO NOT SCALE DRAWING SHEET 1 OF 2

Package Outline and Package Dimensions (16-pin QFN), cont.

IDT® 2 OUTPUT PCIE GEN1/2 SYNTHESIZER

#### REVISIONS REV DESCRIPTION DATE APPROVED INITIAL RELEASE 10/15/08 RC 01 9/17/13 COMBINE POD & LAND PATTERN 3.80 .50 **-** .80 → .25 3.80 2.20 1.80 .50 .80 1.80 NOTES: 1. ALL DIMENSION ARE IN mm. ANGLES IN DEGREES. 2. TOP DOWN VIEW. AS VIEWED ON PCB. 3. COMPONENT OUTLINE SHOW FOR REFERENCE IN GREEN. 4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED. TOLERANCES UNLESS SPECIFIED 6024 Silver Creek Valley Road 5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT San Jose, CA 95138 ® PHONE: (408) 284-8200 DECIMAL ANGULAR XX± ± XXX± FOR SURFACE MOUNT DESIGN AND LAND PATTERN. www.IDT.com FAX: (408) 284-8591 XXXX NL/NLG16 PACKAGE OUTLINE 3.0 x 3.0 mm BODY APPROVALS DATE DRAWN RAC 10/15/08 CHECKED 0.5 mm PITCH QFN REV 01 SIZE DRAWING No. C PSC-4169 DO NOT SCALE DRAWING SHEET 2 OF 2

#### REVISIONS DATE CREATED AUTHOR T. VU REV DESCRIPTION 08/25/98 02 ADD 14 & 16 LD 07/10/99 T. VU 03 ADD 8 LD 5/23/01 ADDED TOPMARK TO TITLE 04 10/14/04 05 ADD "GREEN" PGG NOMENCLATURE TU VU 3/8/13 ADDED PACKAGE CODE RAC 06 9/3/14 ADD TOLERANCE FOR A, A1, E AND b CK LEE 07 R.TANH 3/10/17 08 ADD OPTION T1 NOTE: REFER TO DCP FOR OFFICIAL RELEASE DATE <u>-A-</u> ∕2\ 10 - 20 2X \_\_\_\_\_\_.20 | C | A | B N/2 TIPS -0. WIN E/2 E1 -B-R.09 MIN -H-INDEX AREA (E1/2 X D/2) 1 -GAGE PLANE .25 10°-20° 0.-8. .50MIN -.625NOM-.20 REF .75MAX - 1.00 REF DETAIL B — I.05 (S) SEE DETAIL B -C- SEATING PLANE Α1 ◬

+ bbb (B) C AS BS

WITH PLATING

.09/.16

- BASE METAL

REF

SECTION A-A

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.09/.20

# Package Outline and Package Dimensions (16-pin TSSOP)

2975 Stender Way Santa Clara, CA 95054 PHONE: (408) 727-6116 FAX: (408) 492-8674

> REV 80

SHEET 1 OF 3

TITLE PG/PGG PACKAGE OUTLINE
(PG OR PA TOPMARK CODE)
4.4 mm BODY WIDTH TSSOP .65 mm PITCH

TOLERANCES
UNLESS SPECIFIED
DECIMAL ANGUL
XX± ±
XXX±
XXXX±

ANGULAF

www.IDT.com

SIZE DRAWING No.

DO NOT SCALE DRAWING

IDT5V41065 2 OUTPUT PCIE GEN1/2 SYNTHESIZER

#### REVISIONS AUTHOR CREATED REV DESCRIPTION 08/25/98 02 ADD 14 & 16 LD 07/10/99 03 ADD 8 LD T. VU 5/23/01 04 ADDED TOPMARK TO TITLE 10/14/04 05 ADD "GREEN" PGG NOMENCLATURE TU VU 3/8/13 06 ADDED PACKAGE CODE RAC 07 ADD TOLERANCE FOR A, A1, E AND b CK LEE 9/3/14 3/10/17 08 ADD OPTION T1 NOTE: REFER TO DCP FOR OFFICIAL RELEASE DATE

Packa

P

Outline

and

**Package** 

**Dimensions** 

(16-pin

TSSOP), cont.

SHEET 2 OF 3

2 OUTPUT PCIE GEN1/2 SYNTHESIZER

		PG/P	GG8			PG/P	GG14			PG/PGG16			PG/PGG20					PG/P	GG24			PG/P	<i>3</i> G28					
SYM	JEDE	C VARIAT	ION	N	JEDE	C VARIAT	ION	N	JEDE	JEDEC VARIATION		JEDEC VARIATION  AB				N	JEDE	C VARIAT	ION	N	JEDE	C VARIAT	ION	N	JEDE	C VARIAT	ION	- N
8	LUL		1111	F	1011		1447	I	1.011		1447	F	AUNI		1417	I	1.011		LIAV	Ţ	1.011		LIAV	1 I I				
L	MIN	NOM	MAX	_	MIN	NOM	MAX	_	MIN	NOM	MAX	_	MIN	NOM	MAX		MIN	NOM	MAX	_	MIN	NOM	MAX					
A	.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20					
A1	.05	.10	.15		.05	.10	.15		.05	.10	.15		.05	.10	.15		.05	.10	.15		.05	.10	.15	П				
A2	.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05					
D	2.90	3.00	3.10	4,5	4.90	5.00	5.10	4,5	4.90	5.00	5.10	4,5	6.40	6.50	6.60	4,5	7.70	7.80	7.90	4,5	9.60	9.70	9.80	4,5				
Ε	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3				
E1	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6				
е		.65 BSC				.65 BSC				.65 BSC		.65 BSC				.65 BSC				.65 BSC								
b	.19	.25	.30		.19	.25	.30		.19	.25	.30		.19	.25	.30		.19	.25	.30		.19	.25	.30					
b1	.19	.22	.25		.19	.22	.25		.19	.22	.25		.19	.22	.25		.19	.22	.25		.19	.22	.25					
aaa	_	-	.10		_	_	.10		_	_	.10		_	-	.10		-	-	.10		-	-	.10					
bbb	-	-	.10		_	-	.10		_	-	.10		_	-	.10		-	-	.10		ı	-	.10					
N		8				14				16				20				24				28						

#### NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994
- DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-
- DIMENSION E TO BE DETERMINED AT SEATING PLANE \_\_C\_
- DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE —H—
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
  MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE
- bimension e1 does not include interlead flash or protrusions. Interlead flash or protrusions shall not exceed .25 mm per side
- △ DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
- LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
- 10 ALL DIMENSIONS ARE IN MILLIMETERS
- 11 THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-153, VARIATION AA, AB-1, AB, AC, AD & AE

		OPTIO	N T1								
	PGG14T1										
S Y M B D L	JEDE	N									
B		AB-1		P							
	MIN	NOM	MAX	ÌÈ							
Α	.90	1.10	1.20								
A1	.05	.10	.15								
A2	.80	1.00	1.05								
D	4.90	5.00	5.10	4,5							
E	6.20	6.40	6.60	3							
E1	4.30	4.40	4.50	4,6							
е		.65 BSC									
Ь	.19	.25	.30								
b1	.19	.22	.25								
С	.09	-	.20								
aaa	-	-	.10								
bbb	-	-	.10								
N		14	·								

TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR XX± ± XXX± XXXX±		WW.	<b>IDT™</b> w.IDT.com	2975 Stender Way Santa Clara, CA 95054 PHONE: (408) 727-6116 FAX: (408) 492-8674		
		TITLE 4.	PG/PGG PACKAGE (PG OR PA TOPM 4 mm BODY WIDTH	IARK CODE)	PITCH	
		SIZE	DRAWING No.		REV	
		C	PSC-	-4056	80	

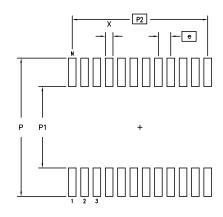
DO NOT SCALE DRAWING

_										
	DATE		REVISIONS							
	CREATED	REV	DESCRIPTION	AUTHO						
	08/25/98	02	ADD 14 & 16 LD	T. VU						
	07/10/99	03	ADD 8 LD	T. VU						
	5/23/01	04	ADDED TOPMARK TO TITLE							
	10/14/04	05	ADD "GREEN" PGG NOMENCLATURE	TU VL						
	3/8/13	06	ADDED PACKAGE CODE	RAC						
	9/3/14	07	ADD TOLERANCE FOR A, A1, E AND b	CK LE						
	3/10/17	08	ADD OPTION T1	R.TAN						
	NOTE:	REFER	TO DCP FOR OFFICIAL RELEASE DATE							

Package Outline and Package Dimensions (16-pin TSSOP), cont.

IDT5V41065 2 OUTPUT PCIE GEN1/2 SYNTHESIZER

# LAND PATTERN DIMENSIONS



	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX
Р	7.20	7.40	7.20	7.40	7.20	7.40	7.20	7.40	7.20	7.40	7.20	7.40
P1	4.20	4.40	4.20	4.40	4.20	4.40	4.20	4.40	4.20	4.40	4.20	4.40
P2	1.95	BSC	3.90 BSC		4.55 BSC		5.85 BSC		7.15 BSC		8.45 BSC	
Х	.30	.50	.30	.50	.30	.50	.30	.50	.30	.50	.30	.50
е	.65 E	3SC	.65 BSC		.65 E	.65 BSC		.65 BSC		3SC	.65 BSC	
N	8	3	14		16		20		24		28	

TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR XX± ± XXX± XXXX±	Www.	IDT™ w.IDT.com	Santa Cla PHONE: (	ender Way ara, CA 95 408) 727– 3) 492–86	6116
	TITLE 4.	PG/PGG PACKAGE (PG OR PA TOPM 4 mm BODY WIDTH	ARK COD	E)	PITCH
	SIZE	DRAWING No.			REV
	С	PSC-	-4056	5	80
	DO NO	OT SCALE DRAWING	SHEET 3	OF 3	

# **Ordering Information**

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
5V41065PGG	See Page 11	Tubes	16-pin TSSOP	0 to +70° C
5V41065PGG8		Tape and Reel	16-pin TSSOP	0 to +70° C
5V41065PGGI		Tubes	16-pin TSSOP	-40 to +85° C
5V41065PGGI8		Tape and Reel	16-pin TSSOP	-40 to +85° C
5V41065NLG	See Page 11	Trays	16-pin QFN	0 to +70° C
5V41065NLG8		Tape and Reel	16-pin QFN	0 to +70° C
5V41065NLGI		Trays	16-pin QFN	-40 to +85° C
5V41065NLGI8		Tape and Reel	16-pin QFN	-40 to +85° C

<sup>&</sup>quot;G" after the two-letter package code are the Pb-Free configuration, RoHS compliant.

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# **Revision History**

Rev.	Originator	Date	Description of Change
Α		07/15/08	New datasheet; Preliminary initial release.
В	RDW	01/13/10	Added Gen2 to title; update Electrical tables per char; added Differential Phase Jitter table.
С	RDW	04/27/10	Updated electrical tables per char; VDD is now 3.3 ±5%; released to final.
D	RDW	07/19/10	Updated title and general description     Updated cycle-to-cycle jitter spec from 125 to 100 ps.
E	RDW	11/21/11	<ol> <li>Changed title to "2 Output PCle GEN1/2 Synthesizer"</li> <li>Added note to Features section: "For PCle Gen3 applications, see 5V41235"</li> <li>Updated Differential Phase Jitter table.</li> </ol>
F	J, Chao	08/26/13	<ol> <li>Added 16VFQFPN notes in Features section</li> <li>Added pinout and "Output/Spread Selection" table for 16VFQFPN.</li> <li>Updated Pin Description table to include VFQFPN pin descriptions.</li> <li>Added Thermal Characteristics table for 16VFQFPN.</li> <li>Added marking diagrams for 16VFQFPN.</li> <li>Added Package Dimensions/Drawing for 16VFQFPN.</li> <li>Updated Ordering Information to include 16VFQFPN.</li> </ol>
G	C.P.	04/17/17	Replaced package outline drawings with latest NLG16 and PGG16 drawings.     Updated legal disclaimer.

# IDT5V41065 2 OUTPUT PCIE GEN1/2 SYNTHESIZER

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